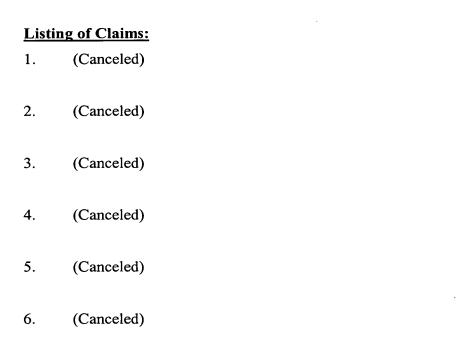
## Amendments to the Claims:

7.

(Canceled)

This listing of claims will replace all prior versions, and listings, of claims in the application:



- 8. (Original) A component of semiconductor processing equipment, said component comprising a liquid crystalline polymer on an outer surface thereof.
- 9. (Original) The component according to Claim 8, wherein the liquid crystalline polymer comprises a coating on a surface of a substrate.
- 10. (Original) The component according to Claim 9, wherein the substrate comprises aluminum or an aluminum alloy.
- 11. (Original) The component according to Claim 9, wherein the substrate comprises alumina.
- 12. (Currently Amended) The component according to Claim 10, wherein the substrate includes an anodized or non-anodized surface.

- 13. (Original) The component according to Claim 9, wherein the liquid crystalline polymer comprises a plasma sprayed coating.
- 14. (Original) The component according to Claim 8, wherein the component is a plasma chamber wall, a chamber liner, a gas distribution plate, a gas ring, a pedestal, an electrostatic chuck and/or a focus ring.
- 15. (Original) The component according to Claim 8, wherein the liquid crystalline polymer comprises a preformed sheet covering a surface of a substrate.
- 16. (Original) The component according to Claim 13, wherein the component comprises a roughened surface in contact with the plasma sprayed coating.
- 17. (Original) The component according to Claim 8, wherein the liquid crystalline polymer contains a filler.
- 18. (Original) A plasma chamber comprising at least one component according to Claim 8.
- 19. (Canceled)
- 20. (Canceled)
- 21. (Canceled)
- 22. (Canceled)
- 23. (Canceled)